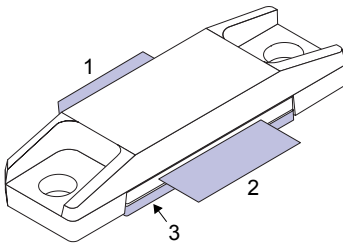


LDMOS L-band radar transistor

STAC780-2B
Features

| Order code | Frequency | V _{DD} | P _{OUT} | Gain | Efficiency |
|--------------|------------------|-----------------|------------------|-------|------------|
| STAC1214-250 | 1200 to 1400 MHz | 36 V | 250 W | 14 dB | 50 % |

- Excellent thermal stability
- Common source configuration
- P_{OUT} = 250W with 14 dB gain over 1200 to 1400 MHz
- ST air-cavity STAC packaging technology

Applications

- Avionics

Description

The STAC1214-250 is a common source N-channel enhancement-mode lateral field-effect RF power transistor designed for L-band radar applications.

| Pin connection | |
|----------------|----------------------|
| Pin | Connection |
| 1 | Drain |
| 2 | Gate |
| 3 | Source (bottom side) |



| Product status link |
|------------------------------|
| STAC1214-250 |

| Product summary | |
|--------------------|--------------|
| Order code | STAC1214-250 |
| Marking | 1214-250 |
| Package | STAC780-2B |
| Packing | Tube |
| Base/bulk quantity | 15/90 |

1 Electrical data

1.1 Maximum ratings

Table 1. Absolute maximum ratings (T_{CASE} = +25 °C)

| Symbol | Parameter | Value | Unit |
|----------------------|---|-------------|------|
| V _{(BR)DSS} | Drain-source voltage | 80 | V |
| V _{GS} | Gate-source voltage | ±20 | V |
| P _{DISS} | Power dissipation (at T _{CASE} = +70 °C) | 928 | W |
| T _J | Maximum operating junction temperature | +200 | °C |
| T _{STG} | Storage temperature range | -65 to +150 | °C |

1.2 Thermal data

Table 2. Thermal data

| Symbol | Parameter | Value | Unit |
|-----------------------|----------------------------------|-------|------|
| R _{thj-case} | Junction-case thermal resistance | 0.14 | °C/W |

Note: Thermal data at 100 μs - 10%

1.3 ESD protection characteristics

Table 3. ESD protection

| Symbol | Test methodology | Class |
|--------|------------------------------------|-------|
| HBM | Human body model (per JESD22-A114) | 0 |

2 Electrical characteristics

($T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified)

2.1 Static

Table 4. Static

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|---|---|------|------|------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $V_{GS} = 0\text{ V}$, $I_{DS} = 10\text{ mA}$ | 80 | | | V |
| I_{DSS} | Zero gate voltage drain leakage current | $V_{GS} = 0\text{ V}$, $V_{DS} = 28\text{ V}$ | | | 2 | μA |
| I_{GSS} | Gate-source leakage current | $V_{GS} = 15\text{ V}$, $V_{DS} = 0\text{ V}$ | | | 1 | μA |
| $V_{GS(Q)}$ | Gate quiescent voltage | $V_{DS} = 28\text{ V}$, $I_{DS} = 150\text{ mA}$ | 2.0 | | 5.0 | V |
| $V_{DS(on)}$ | Drain-source on voltage | $V_{GS} = 10\text{ V}$, $I_{DS} = 6\text{ A}$ | | 550 | 600 | mV |
| G_{FS} | Forward transconductance | $V_{DS} = 10\text{ V}$, $I_{DS} = 6\text{ A}$ | 2.5 | | | S |

2.2 Dynamic

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|------------------|--|------|------|------|------|
| f | Frequency | | 1200 | | 1400 | MHz |
| P_{OUT} | Output power | $P_{IN} = 10\text{ W}$ | 250 | 260 | | W |
| G_{PS} | Power gain | $P_{OUT} = 250\text{ W}$ | 13 | 14 | | dB |
| η_D | Drain efficiency | $P_{OUT} = 250\text{ W}$ | 50 | | | % |
| t_r | Rise time | $P_{OUT} = 250\text{ W}$ | | | 100 | ns |
| t_f | Fall time | $P_{OUT} = 250\text{ W}$ | | | 30 | ns |
| ΔG_{PS} | Gain variation | $P_{OUT} = 250\text{ W}$, gain droop within the pulse | | | 0.25 | dB |
| VSWR | Load mismatch | All phase angles at $P_{OUT} = 250\text{ W}$ | | | 10:1 | |

Note: $V_{DD} = 36\text{ V}$, $I_{DQ} = 150\text{ mA}$, pulse width = 100 μs , duty cycle = 10%.

3 Impedance data

Figure 1. Impedance data

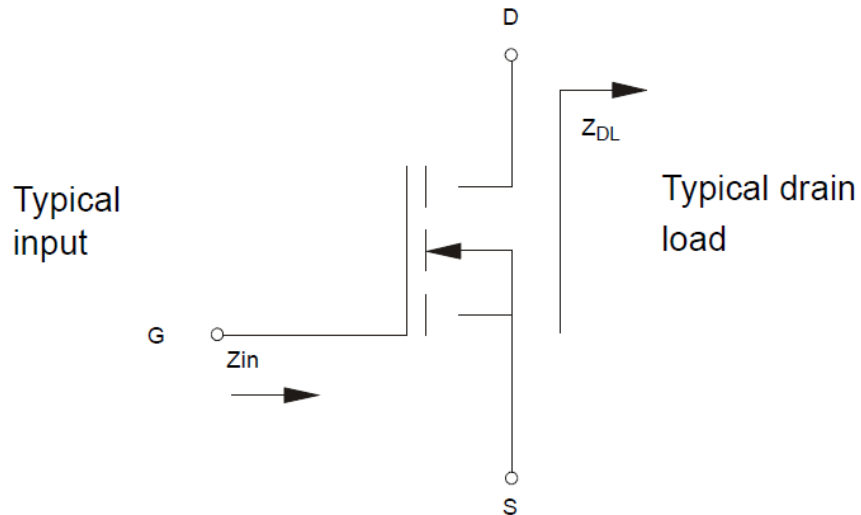
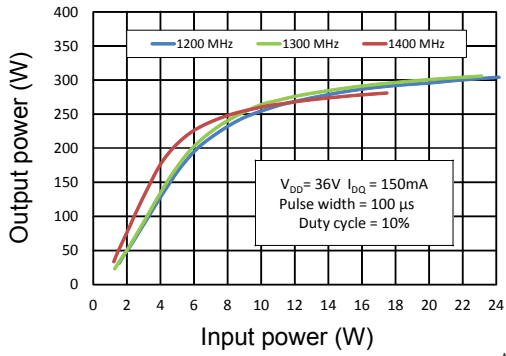


Table 6. Impedance data

| Frequency (MHz) | Z_{source} (Ohm) | Z_{load} (Ohm) |
|-----------------|--------------------|------------------|
| 1200 | 1.1+j1.9 | 1.5+j2.8 |
| 1300 | 1.0+j3.1 | 1.5+j3.1 |
| 1400 | 1.4+j4.3 | 1.0+j3.6 |

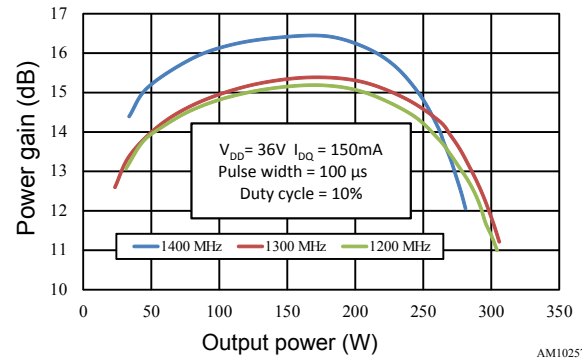
4 Typical performances

Figure 2. Output power vs input power



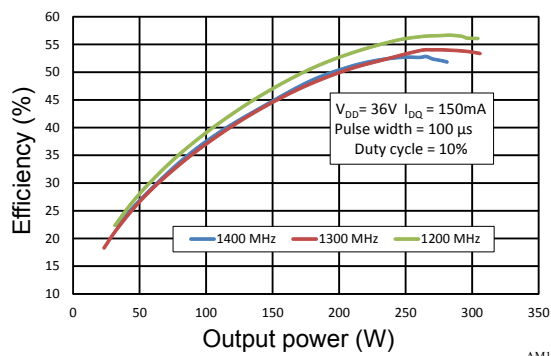
AM10258V

Figure 3. Power gain vs output power



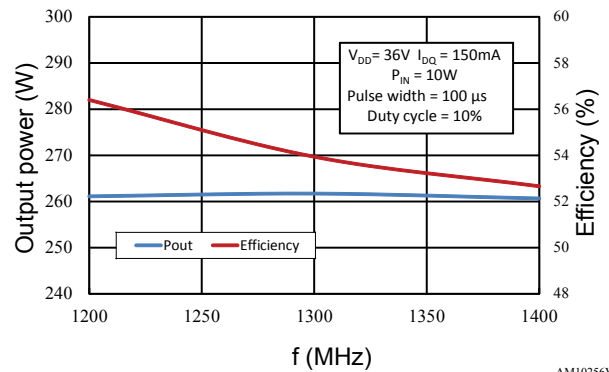
AM10257V

Figure 4. Efficiency vs output power



AM10259V

Figure 5. Output power and efficiency vs frequency

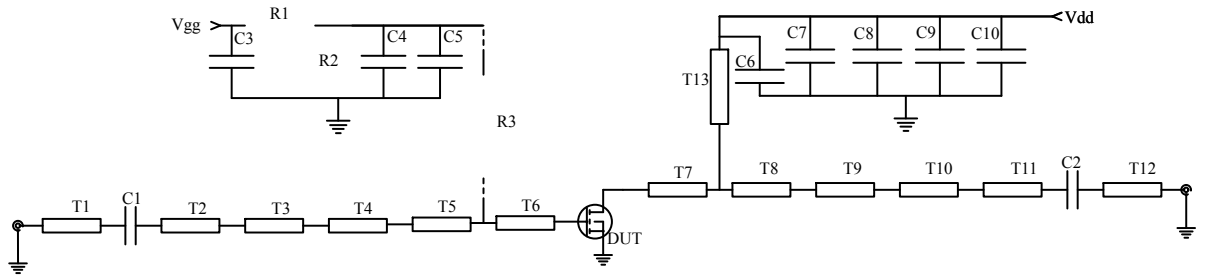


AM10256V

5 Test circuit

5.1 Electrical schematic and BOM

Figure 6. Electrical schematic



GADG060420201037SA

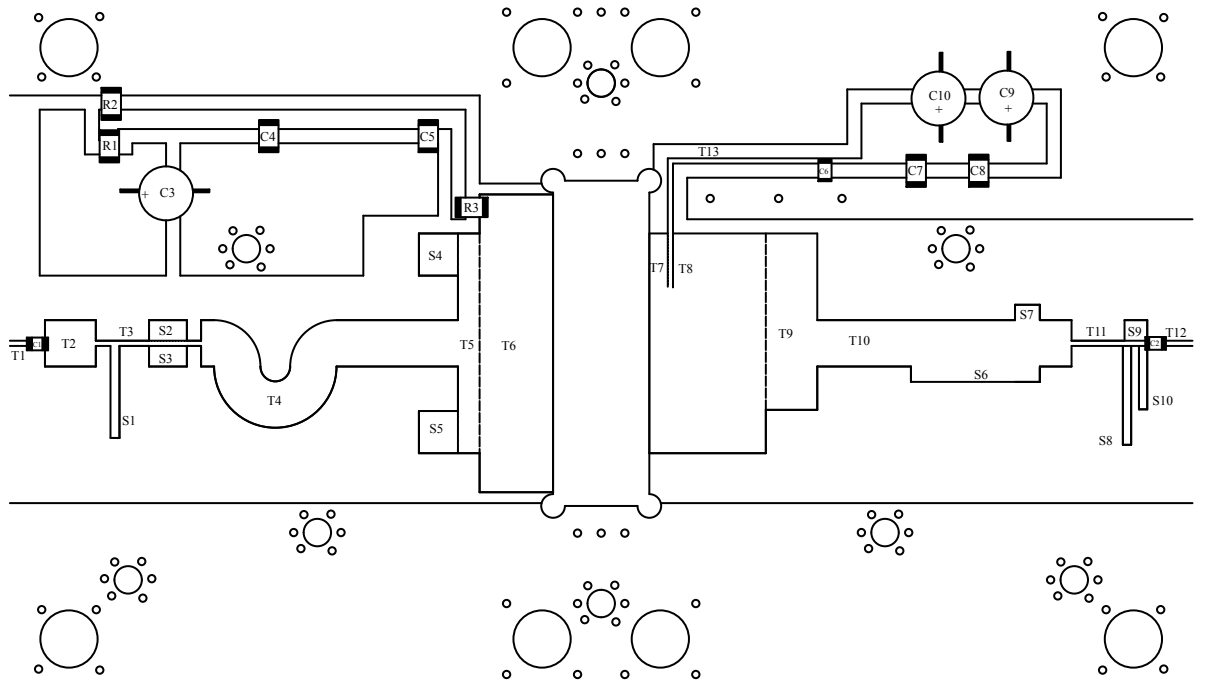
Table 7. Component list

| Component | Description | Dimension (X,Y) | Values |
|-----------|----------------------------|--------------------|--------|
| TL1 | Stripline | L=0.111" W=0.022" | |
| TL2 | Stripline | L=0.304" W=0.022" | |
| TL3 | Stripline | L=1.74" W=0.196" | |
| TL4 | Stripline | L=0.402" W=0.929" | |
| TL5 | Stripline | L=0.100" W=0.929" | |
| TL6 | Stripline | L=0.368" W=0.929" | |
| TL7 | Stripline | L=1.136" W1=0.196" | |
| TL8 | Stripline | L=0.165" W=0.109" | |
| TL9 | Stripline | L=0.341" W=0.022" | |
| TL10 | Stripline | L=0.145" W=0.221" | |
| S1 | Shim | L=0.048" W=0.091" | |
| S2 | Shim | L=0.048" W=0.091" | |
| S3 | Shim | L=0.105" W=0.091" | |
| S4 | Shim | L=0.105" W=0.091" | |
| S5 | Shim | L=0.050" W=0.361" | |
| S6 | Shim | L=0.022" W=0.303" | |
| S7 | Shim | L=0.105" W=0.069" | |
| S8 | Shim | L=0.048" W=0.187" | |
| S9 | Shim | L=0.158" W=0.069" | |
| S10 | Shim | L=0.105" W=0.069" | |
| S11 | Shim | L=0.105" W=0.069" | |
| S12 | Shim | L=0.022" W=0.424" | |
| C1, C2 | ATC100A300J chip capacitor | | 30 pF |
| C3 | ATC100B101 chip capacitor | | 100 pF |

| Component | Description | Dimension (X,Y) | Values |
|----------------|--|-----------------|--------------|
| C4 | ATC100B910 chip capacitor | | 91 pF |
| C5 | 220 μ F, 63 V Electrolytic capacitor | | 220 μ F |
| C6 | ATC100B390 chip capacitor | | 39 pF |
| C7 | ATC700B122JT chip capacitor | | 1200 pF |
| C8 | 1000 μ F, 63 V Electrolytic capacitor | | 1000 μ F |
| C9 | 100 μ F, 100 V Electrolytic capacitor | | 100 μ F |
| R1 | CR1206-8W-102JB | | 1 k Ω |
| R2 | CR1206-8W-202JB | | 2 k Ω |
| R3 | CR1206-8W-501JB | | 50 Ω |
| Board material | Rogers Duroid 6010 Er = 10.2, Th = 0.64 mm | 3X5" | |

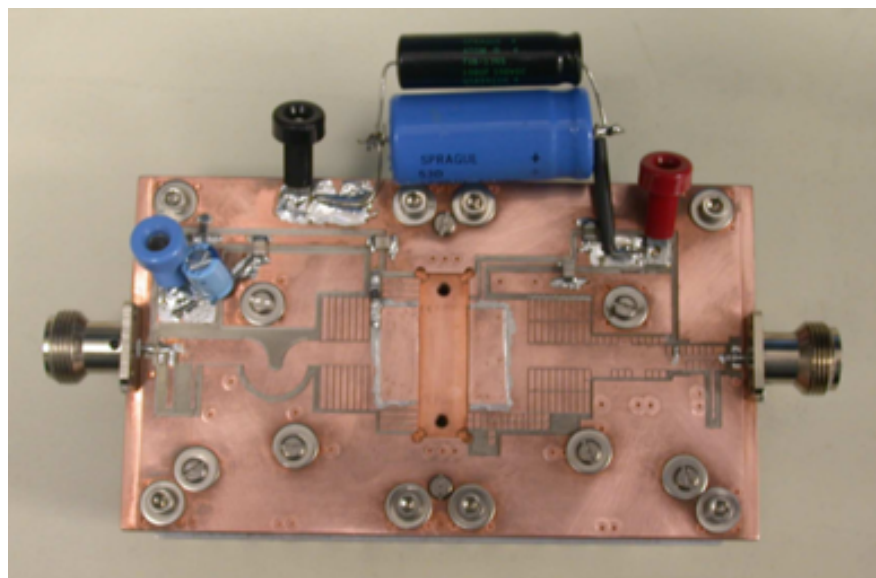
5.2 Test circuit layout

Figure 7. Broadband 1200-1400 MHz test circuit layout



AM12366v1

Figure 8. Demonstration board picture



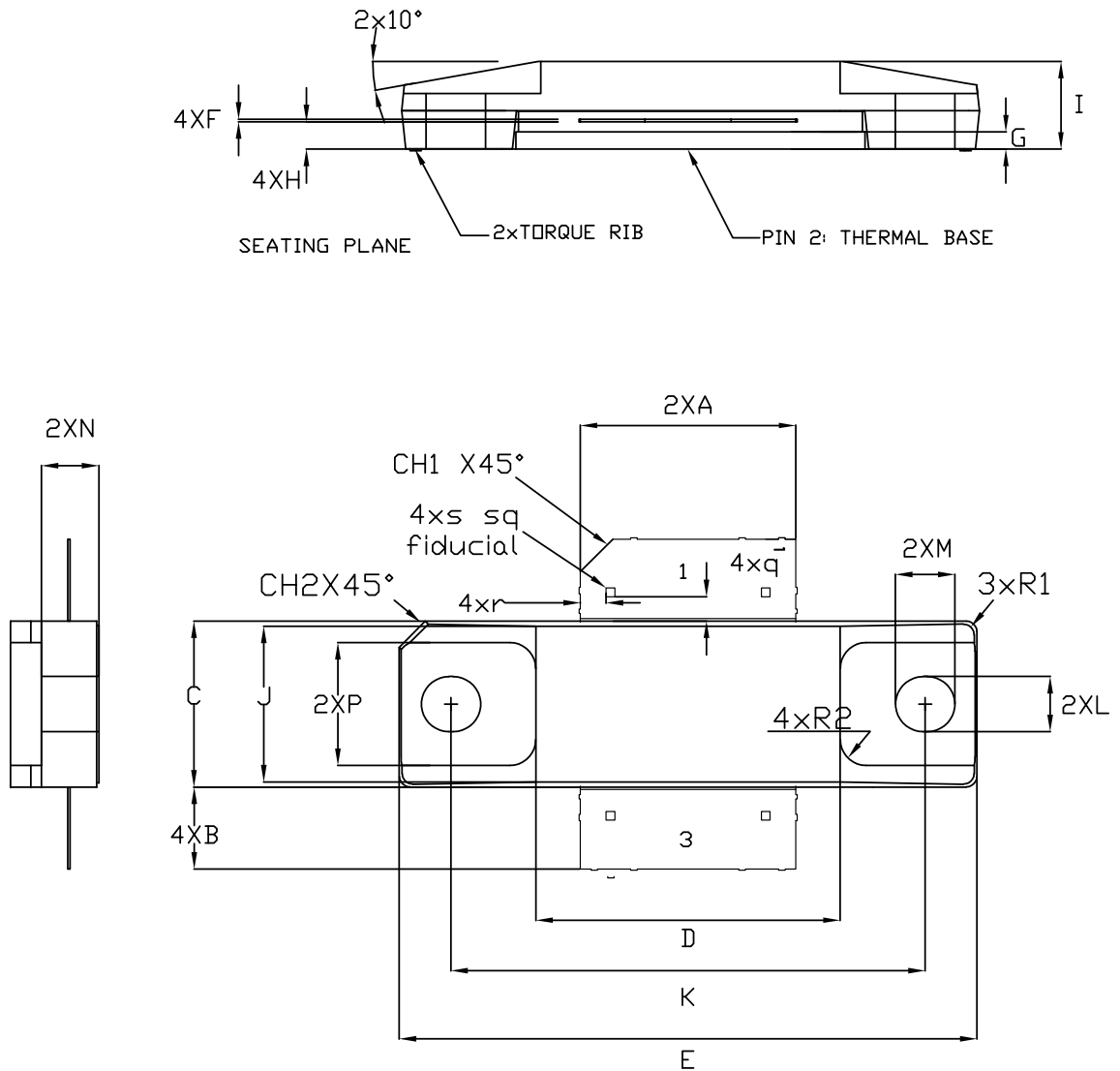
AM12371v1

6 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

6.1 STAC780-2B package information

Figure 9. STAC780-2B package outline



| PIN | CONNECTION |
|-----|------------|
| 1 | DRAIN |
| 2 | SOURCE |
| 3 | GATE |

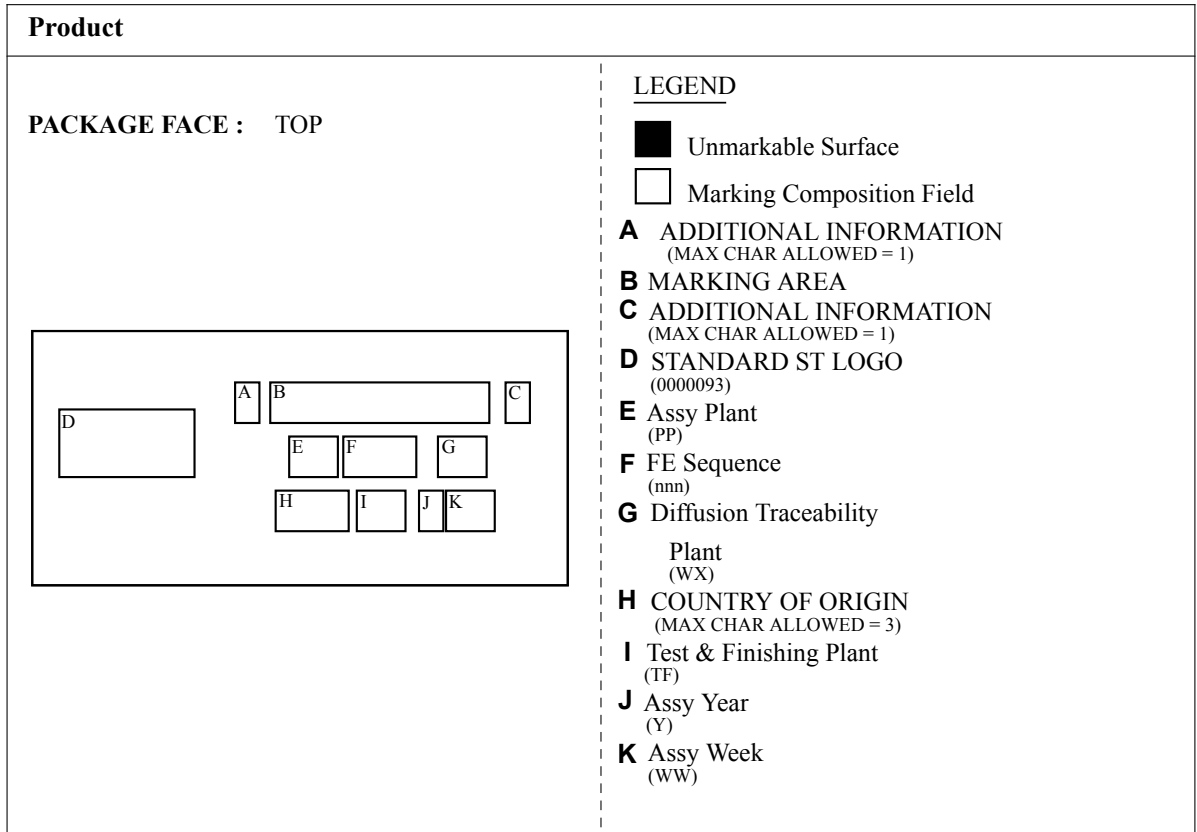
DM00481924_2

Table 8. STAC780-2B mechanical data

| Ref. | Millimeters | | |
|------|-------------|------|-------|
| | Min. | Typ. | Max. |
| A | 12.65 | | 12.75 |
| B | 4.57 | | 5.08 |
| C | 9.65 | | 9.91 |
| D | 17.78 | | 18.08 |
| E | 33.88 | | 34.19 |
| F | 0.11 | | 0.17 |
| G | 0.97 | | 1.14 |
| H | 1.52 | | 1.70 |
| I | 4.83 | | 5.33 |
| J | 9.52 | | 9.78 |
| K | 27.69 | | 28.19 |
| L | 3.20 | 3.25 | 3.30 |
| M | 3.43 | 3.51 | 3.58 |
| N | 3.30 | 3.38 | 3.45 |
| p | 7.14 | 7.21 | 7.29 |
| q | | 1.37 | |
| r | | 1.52 | |
| R1 | | 0.63 | |
| R2 | | 1.52 | |
| s | | 0.51 | |
| θ | | 10° | |
| CH1 | | 2.72 | |
| CH2 | | 1.52 | |

6.2 STAC780-2B marking information

Figure 10. STAC780-2B marking information



CD00362879_13

Revision history

Table 9. Document revision history

| Date | Version | Changes |
|-------------|---------|--|
| 27-Jan-2012 | 1 | First release |
| 06-Jun-2012 | 2 | <ul style="list-style-type: none"> – Modified: <i>Figure 7</i> – Added: <i>Figure 8</i> – Updated the entire <i>Table 7</i> |
| 24-Sep-2012 | 3 | Updated title on the coverpage and <i>Table 4</i> . |
| 20-May-2014 | 4 | Updated <i>Table 8: STAC265B mechanical data</i> . Minor text changes. |
| 03-Apr-2020 | 5 | Updated <i>Section 6.1 STAC780-2B package information</i> and datasheet modified accordingly. Added <i>Table 3. ESD protection</i> . Minor text changes. |
| 13-Jul-2020 | 6 | Modified features table on cover page. |

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